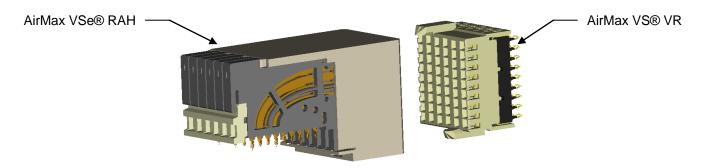
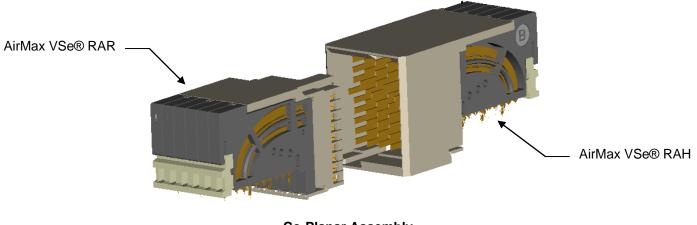
NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Amphe	nol ICC
ITLE			PAGE 1 of 13	REVISION
	AirMax VSe	e®,VS2® Connector System	AUTHORIZED BY Terry Luo	DATE 2021-02-03
			CLASSIFICATION UNREST	RICTED
	AirMax VS® VH -		AirMax VS	e® RAR

Backpanel Header with RAR on Daughter Card



Backpanel Receptacle with RAH on Daughter Card



Co-Planar Assembly

AirMax VSe@,VS2@ Connector System 2 of 13 E AUTHRAZEDE VIE DATE 221-02- CLASSFECATION UNRESTRICTED 0 OBJECTIVE UNRESTRICTED 0 RATTINGS UNRESTRICTED 0 RATTINGS UNRESTRICTED 0 RATTINGS UNRESTRICTED 0 RATTINGS Image: Construction of the constructin the construction of the construction of the consth	NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Amphe	nol ICC
AirMax VSe@,VS2@ Connector System Intervice by Description Description Description Description 0 OBJECTIVE	TITLE				
Image: Construction 2021-02- Construction UNRESTRICTED Image: Construction UNRESTRICTED Image: Construction Image: Construction Image: Co		AirMax VSe®.VS	2® Connector System	AUTHORIZED BY	
UNRESTRICTED UNRESTRICTON FORCE UNRESTRICTED		,		-	2021-02-03
0 SCOPE 0 RATINGS 0 RATINGS 1 FCI SPECIFICATIONS 2 NOUSTRY OR TRADE ASSOCIATION STANDARDS 4.1 FCI SPECIFICATIONS 4.1 FCI SPECIFICATIONS 4.1 FCI ADRORATOR R REPORTS 5.2 NATIONAL OR INTERNATIONAL STANDARDS 4.5 SATETY AGENCY APROVALS 60 REQURRENTS 51 QUALIFICATION 52 MATERIAL 53 FNINI 54 DESIGN AND CONSTRUCTION 54 DESIGN AND CONSTRUCTION 61 CONSTRUCTION 62 INSULATION RESISTANCE 63 DIFLECTRICAL CHARACTERISTICS 64 CURRENT RATING 65 MECHANICAL CHARACTERISTICS 71 MATING FORCE 72 COMPLIANT PIN INSERTION FORCE 73 COMPLIANT PIN INSERTION FORCE 74 PCB HOLE DEPROMENT RADIUS AND REMAINING CU PLATING THICKNESS 75 PCB HOLE DEPROMENT RADIUS AND REMAINING CU PLATING THICKNESS 76 PCB HOLE DEPROMENT RADIUS AND REMAINING CU PLATING THIC					RICTED
0 RATINGS 0 APPLICABLE DOCUMENTS 1. PGI SPECIPICATIONS 4.1 PGI DECIPICATIONS 4.2 DIDESTRY OR TRADE ASSOCIATION STANDARDS 4.3 NATIONAL OR INTERNATIONAL STANDARDS 4.4 PGI LABORATORY REPORTS 5.4 SAFETY AGENCY APPROVALS 6.0 REQUREMENTS 5.1 QUALIFICATION 5.4 DESIGN AND CONSTRUCTION 6.0 ELECTRICAL CHARACTERISTICS 6.1 CONTRUCT RESISTANCE, LOW LEVEL 6.2 Insulation RESISTANCE 6.3 DISIGN AND CONSTRUCTION 6.4 CURRENT RATING 7.5 INSULATION RESISTANCE 6.4 CURRENT RATING 7.5 INSULATION RESISTANCE 7.6 MACTERIC WITHATIONING VOLTAGE 6.7 COMPLIANT PIN INSERTION FORCE 7.6 COMPLIANT PIN INSERTION FORCE 7.6 COMPLIANT PIN INSERTION FORCE 7.7 COMPLIANT PIN INSERTION FORCE 7.8 PCB HOLE DEPERGRAVATION RADUES AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE DEPERGRAVITION RADUES AND REMAININ	1.0	OBJECTIVE			
0 APPLICABLE DOCUMENTS 1 FCI SPECIFICATIONS 42 INDUSTRY OR TRADE ASSOCIATION STANDARDS 43 NATIONAL OR INTERNATIONAL STANDARDS 44 FCI LABORATORY REPORTS 55 SAFETY ACENCY APPROVALS 60 REQURRMENTS 51 QUALIFICATION 52 MATERIAL 53 FNINH 54 DESIGN AND CONSTRUCTION 55 MATERIAL 56 DESIGN AND CONSTRUCTION 57 DESIGN AND CONSTRUCTION 58 DESIGN AND CONSTRUCTION 59 DESIGN AND CONSTRUCTION 50 ELECTRICAL CHARACTERISTICS 61 CONTACT RESISTANCE, LOW LEVEL 62 INSULATION RESISTANCE 63 DIELECTRIC WITHSTANDING VOLTAGE 64 CURRENT RATING, CONTACT RESISTANCE 71 MATING/UN MATING FORCE 72 COMPLIANT PLANTERTINON FORCE 73 COMPLIANT PLANTERTINON FORCE 74 PCB HOLE DEFORMATION RADUS AND REMAINING CUP PLATING THICKNESS 75 PCB HOLE WALL DAMAGE 74 PCB	2.0	SCOPE			
4.1 FCI SPECIFICATIONS 4.2 INDUSTRY OR TRADE ASSOCIATION STANDARDS 4.3 NATORAL OR INTERNATIONAL STANDARDS 4.4 FCI LABORATORY REPORTS 4.5 SAFETY AGENCY APPROVALS 0 REQUIREMENTS 5.1 QUALIFICATION 5.2 MATERIAL 5.3 FINSH 5.4 DESIGN AND CONSTRUCTION 0 ELECTRICAL CHARACTERISTICS 6.1 CONTACT RESISTANCE, LOW LEVEL 6.2 NSULATION RESISTANCE 6.3 DIELECTRIC WITHSTANDING VOLTAGE C.4 CURENT RATING. 7.1 MATING/UN-MATING FORCE 7.2 COMPLIANT PIN RESTRICTO FORCE 7.3 COMPLIANT PIN RESTRICTO FORCE 7.4 PCB HOLE DEFORMATION RADUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE DEFORMATION RADUS AND REMAINING CU PLATING THICKNESS 7.4 PCB HOLE DEFORMATION RADUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE 8.1 THERMAL SHOCK 2.2 CYCLICAL HUNDINTY AND TEMPERATURE 8.3 THEMERMALSHOCK 8.4	3.0	RATINGS			
42 INDUSTRY OR TRADE ASSOCIATION STANDARDS	4.0	APPLICABLE DOCUMENTS			
4.3 NATIONAL OR INTERNATIONAL STANDARDS 4.4 FCI LABORATORY REPORTS 4.5 SAFETY AGENCY APPROVALS 5.0 REQUIREMENTS 5.1 QUALIFICATION 5.2 MATERIAL 5.3 FINSH 5.4 DESIGN AND CONSTRUCTION 5.4 DESIGN AND CONSTRUCTION 5.4 DESIGN AND CONSTRUCTION 5.6 CONTACT RESISTANCE, LOW LEVEL 6.1 CONTACT RESISTANCE, LOW LEVEL 6.2 INSULATION RESISTANCE 6.3 DELECTRIC WITHSTANDINN OUTAGE 6.4 CURRENT RATING 0 MECHANICAL CHARACTERISTICS 7.1 MATING/UN-MATING FORCE 7.2 COMPLIANT PIN NERTION FORCE 7.4 PCB HOLE DEPORMATION RADUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE DEPORMATION RADUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE DEPORMATION RADUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE DEPORMATION RADUS AND REMAINING CU PLATING THICKNESS 8.1 THERMAL SHOCK 8.2 CYCLICAL HUMDITY AND TEMPERATURE 8.1 THERMAL SHOCK					
44 FCI LABORATORY REPORTS					
4.5 SAFETY AGENCY APPROVALS 0 REQUIREMENTS 5.1 QUALIFCATION 5.2 MATERAL 5.3 FINSH 5.4 DESIGN AND CONSTRUCTION 0 ELECTRICAL CHARACTERISTICS 6.1 CONTACT RESISTANCE, LOW LEVEL 6.2 INSULATION RESISTANCE 6.3 DIELECTRIC WITHSTANDING VOLTAGE 6.4 CURRENT RATING 7.1 MATING/UN-MATING FORCE 7.2 COMPLIANT PIN INSERTION FORCE 7.4 MATING/UN-MATING FORCE 7.5 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL CONDITIONS 8.1 THERMAL SHOCK 8.2 CYCLICAL HUMIDITY AND TEMPERATURE 8.3 TEMPERATURE LIFE 8.4 MIXED FLOWING GAS COROSION 8.5 SALT SPRAY 8.6 VIBRATION 8.7 MECHANICAL SHOCK 8.8 DUST 8.10 DISTURE 9.0 UST <td< td=""><td></td><td></td><td></td><td></td><td></td></td<>					
5.1 QUALIFICATION 5.2 MATERIAL 5.3 FINSH 5.4 DESIGN AND CONSTRUCTION 0 ELECTRICAL CHARACTERISTICS 6.1 CONTACT RESISTANCE, LOW LEVEL 6.2 INSULATION RESISTANCE 6.3 DELECTRIC WINSTANDEN VOLTAGE 6.4 CURRENT RATING 0 MECHANICAL CHARACTERISTICS 0.1 MATING/UN-MATING FORCE 7.2 COMPLIANT PIN INSERTION FORCE 7.3 COMPLIANT PIN INSERTION FORCE 7.4 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE 7.6 POLE MOLE DEMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.7 PCB HOLE WALL DAMAGE 8.0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK. 8.2 CYCLACL HUMIDITY AND TEMPERATURE 8.3 TEMPERATURE LIFE 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SHRAY. 8.6 VIBRATION 8.7 MUMIENT FLOWING GAS CORROSION 8.8 DURABILITY. 8.9 <td></td> <td></td> <td></td> <td></td> <td></td>					
5.2 MATERIAL 5.3 FINISH 5.4 DESIGN AND CONSTRUCTION 0 ELECTRICAL CHARACTERISTICS 6.1 CONTACT RESISTANCE, LOW LEVEL 6.2 INSULATION RESISTANCE 6.3 DIELECTRIC WITHSTANDING VOLTAGE 6.4 CURRENT RATING 7.1 MATINOUN-MATING FORCE 7.2 COMPLIANT PIN INSERTION FORCE 7.3 COMPLIANT PIN RETENTION FORCE 7.4 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE BEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE BEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE 0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK. 8.2 CYCLICAL HUMIDITY AND TEMPERATURE 8.3 TEMPERATURE LIFE. 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY. 8 DURABUITY. 9 DUIT. 8.10 DISTURE 9.11 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS.	5.0	REQUIREMENTS			
5.3 FINISH 5.4 DESIGN AND CONSTRUCTION 0. ELECTRICAL CHARACTERISTICS 6.1 CONTACT RESISTANCE, LOW LEVEL 6.2 INSULATION RESISTANCE 6.3 DIELECTRU WITHSTANDING VOLTAGE 6.4 CURRENT RATING 0. MECHANICAL CHARACTERISTICS 7.1 MATING/UN-MATING FORCE 7.2 COMPLIANT PIN INSERTION FORCE 7.3 COMPLIANT PIN NERETION FORCE 7.4 PCB HOLE DEFORMATION RADUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE MALL DAMAGE 0. ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK 8.2 CYCLICAL HUMIDITY AND TEMPERATURE 8.3 TEMPERATURE LIFE 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY 8.6 VIBRATION 8.7 MECHANICAL SHOCK 8.8 DURABULITY 8.9 DUST 8.10 DISTURB 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS 9.3 SAMELEQUIPMENT CALIBRATION <t< td=""><td>5.1</td><td>QUALIFICATION</td><td></td><td></td><td></td></t<>	5.1	QUALIFICATION			
5.4 DESIGN AND CONSTRUCTION 0 ELECTRICAL CHARACTERISTICS 6.1 CONTACT RESISTANCE, LOW LEVEL 6.2 INSULATION RESISTANCE 6.3 DIELECTRIC WITHSTANDING VOLTAGE 6.4 CURRENT RATING 0 MECHANICAL CHARACTERISTICS 7.1 MATING/UN-MATING FORCE 7.2 COMPILANT PIN INSERTION FORCE 7.3 COMPILANT PIN REFENTION FORCE 7.4 PCB HOLE DEPERMATION RADUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE DEPERMATION RADUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE MAIL O AMAGE 0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK 8.2 CYCLICAL HUMIDITY AND TEMPERATURE 8.3 TEMPERATURE LIFE. 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY 8.6 VIBRATION. 8.7 MECHANICAL SHOCK. 8.8 DURABILITY 9.9 DUST 8.10 DISTURB 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS. 9.1					
0 ELECTRICAL CHARACTERISTICS					
6.1 CONTACT RESISTANCE, LOW LEVEL 6.2 INSULATION RESISTANCE. 6.3 DIELECTRIC WITHSTANDING VOLTAGE 6.4 CURENT RATING. 0 MECHANICAL CHARACTERISTICS. 7.1 MATING/UN-MATING FORCE 7.2 COMPLIANT PIN INSERTION FORCE 7.3 COMPLIANT PIN INSERTION FORCE 7.4 PCB HOLE DEFORMATION RADIUS AND REMAINING CUPLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE 0 ENVIRONMENTAL CONDITIONS. 8.1 THERMAL SHOCK. 8.2 CYCLICAL HUMIDITY AND TEMPERATURE 8.3 TEMPERATURE LIFE. 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY. 8.6 VIBRATION. 8.7 MECHANICAL SHOCK. 8.8 DURABILITY. 8.9 DUST. 8.10 DISTURB. 0 QUALITY ASSURANCE PROVISIONS 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS. 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING.<					
6.2 INSULATION RESISTANCE	5.0				
6.3 DIELECTRIC WITHSTANDING VOLTAGE 6.4 CURRENT RATING .0 MECHANICAL CHARACTERISTICS 7.1 MATING/UN-MATING FORCE 7.2 COMPLIANT PIN INSERTION FORCE 7.3 COMPLIANT PIN INSERTION FORCE 7.4 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE .0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK. 8.2 CYCLICAL HUMIDITY AND TEMPERATURE 8.3 TEMPERATURE LIFE. 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY 8.6 VIBRATION 8.7 MECHANICAL SHOCK. 8.8 DURABLITY 8.9 DUST. 8.10 DISTURB 8.10 DISTURB 9.1 EQUIPMENT CALIBRATION					
6.4 CURRENT RATING. 0 MECHANICAL CHARACTERISTICS. 7.1 MATING/UN-MATING FORCE 7.2 COMPLIANT PIN INSERTION FORCE 7.3 COMPLIANT PIN RETENTION FORCE 7.4 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE 0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK. 8.2 CYCLICAL HUMIDITY AND TEMPERATURE. 8.3 TEMPERATURE LIFE. 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY. 8.6 VIBRATION. 8.7 MECHANICAL SHOCK. 8.8 DURABILITY. 8.9 DUST					
7.1 MATING/UN-MATING FORCE 7.2 COMPLIANT PIN INSERTION FORCE 7.3 COMPLIANT PIN RETENTION FORCE 7.4 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE 0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK. 8.2 CYCLICAL HUMIDITY AND TEMPERATURE 8.3 TEMPERATURE LIFE. 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY. 8.6 VIBRATION. 8.7 MECHANICAL SHOCK. 8.8 DURABILITY. 8.9 DUST 8.10 DISTURB. 0 QUALITY ASSURANCE PROVISIONS 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS. 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING. 9.6 RE-QUALIFICATION TESTING. 9.7 QUALIFICATION TESTING.					
7.2 COMPLIANT PIN INSERTION FORCE 7.3 COMPLIANT PIN RETENTION FORCE 7.4 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE. 0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK. 8.2 CYCLICAL HUMIDITY AND TEMPERATURE. 8.3 TEMPERATURE LIFE 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY 8.6 VIBRATION. 8.7 MECHANICAL SHOCK. 8.8 DURABILITY. 8.9 DUST 8.10 DISTURB 8.10 DISTURB 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING 9.7 QUALIFICATION TESTING	7.0	MECHANICAL CHARACTERIST	ICS		
7.2 COMPLIANT PIN INSERTION FORCE 7.3 COMPLIANT PIN RETENTION FORCE 7.4 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE. 0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK. 8.2 CYCLICAL HUMIDITY AND TEMPERATURE. 8.3 TEMPERATURE LIFE 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY 8.6 VIBRATION. 8.7 MECHANICAL SHOCK. 8.8 DURABILITY. 8.9 DUST 8.10 DISTURB 8.10 DISTURB 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING 9.7 QUALIFICATION TESTING	7.1	MATING/UN-MATING FORCE			
7.4 PCB HOLE DEFORMATION RADIUS AND REMAINING CU PLATING THICKNESS 7.5 PCB HOLE WALL DAMAGE 0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK. 8.2 CYCLICAL HUMIDITY AND TEMPERATURE. 8.3 TEMPERATURE LIFE. 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY 8.6 VIBRATION 8.7 MECHANICAL SHOCK. 8.8 DURABILITY 8.9 DUST 8.10 DISTURB. 0 QUALITY ASSURANCE PROVISIONS 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS. 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE. 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING 9.7 QUALIFICATION TEST TABLES.					
7.5 PCB HoLe WALL DAMAGE 0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK 8.2 CYCLICAL HUMDITY AND TEMPERATURE 8.3 TEMPERATURE LIFE 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY 8.6 VIBRATION 8.7 MECHANICAL SHOCK 8.8 DURABILITY 8.9 DUST 8.10 DISTURB 8.10 DISTURB 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING 9.7 QUALIFICATION TESTING					
0 ENVIRONMENTAL CONDITIONS 8.1 THERMAL SHOCK. 8.2 CYCLICAL HUMIDITY AND TEMPERATURE. 8.3 TEMPERATURE LIFE. 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY. 8.6 VIBRATION 8.7 MECHANICAL SHOCK. 8.8 DURABILITY. 8.9 DUST 8.10 DISTURB 8.10 DISTURB 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING 9.7 QUALIFICATION TESTING					
8.1 THERMAL SHOCK					
8.2 CYCLICAL HUMIDITY AND TEMPERATURE. 8.3 TEMPERATURE LIFE. 8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY. 8.6 VIBRATION 8.7 MECHANICAL SHOCK. 8.8 DURABILITY. 8.9 DUST 8.10 DISTURB 8.10 DISTURB 9.1 EQUIPMENT CALIBRATION . 9.2 INSPECTION CONDITIONS. 9.3 SAMPLE QUANTITY AND DESCRIPTION . 9.4 ACCEPTANCE . 9.5 QUALIFICATION TESTING . 9.6 RE-QUALIFICATION TESTING . 9.7 QUALIFICATION TEST TABLES .	3.0				
8.3 TEMPERATURE LIFE					
8.4 MIXED FLOWING GAS CORROSION 8.5 SALT SPRAY 8.6 VIBRATION 8.7 MECHANICAL SHOCK 8.8 DURABILITY 8.9 DUST 8.10 DISTURB 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING 9.7 QUALIFICATION TESTING					
8.5 SALT SPRAY					
 8.7 MECHANICAL SHOCK		SALT SPRAY			
8.8 DURABILITY	8.6				
 8.9 DUST					
8.10 DISTURB. .0 QUALITY ASSURANCE PROVISIONS 9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING 9.7 QUALIFICATION TEST TABLES					
9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING 9.7 QUALIFICATION TEST TABLES					
9.1 EQUIPMENT CALIBRATION 9.2 INSPECTION CONDITIONS 9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING 9.7 QUALIFICATION TEST TABLES	9.0	OUALITY ASSURANCE PROVIS	IONS		
9.2 INSPECTION CONDITIONS	9.1	-			
9.3 SAMPLE QUANTITY AND DESCRIPTION 9.4 ACCEPTANCE 9.5 QUALIFICATION TESTING 9.6 RE-QUALIFICATION TESTING. 9.7 QUALIFICATION TEST TABLES.		-			
9.5 QUALIFICATION TESTING					
9.6 Re-QUALIFICATION TESTING 9.7 QUALIFICATION TEST TABLES					
9.7 QUALIFICATION TEST TABLES					
REVISION RECORD	9./	QUALIFICATION TEST TABLES			
	REV	ISION RECORD			

NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Amphen	
TITLE			PAGE 3 of 13	REVISION E
	AirMax VSe®,\	/S2® Connector System	AUTHORIZED BY Terry Luo	DATE 2021-02-03
				CTED

1.0 Objective

This specification defines the performance, test, quality and reliability requirements of the AirMax VSe® press-fit product.

2.0 Scope

This specification is applicable to the AirMax VSe® press-fit family of products, which provides a high speed board-to-board interconnect for differential pairs and single-ended lines. Connectors include 3-pair, 4-pair and 5-pair backpanel RAR and 3-pair RAH on 2mm column pitch. For backpanel applications, the VSe® RAR will be mated to VS® VH or a VSe® RAH will be mated to a VS® VR. The test sequences defined in this specification meet the intent of Telcordia GR-1217-CORE requirements.

3.0 Ratings

- 3.1 Operating Voltage Rating
 - Agency Voltage Rating < 30 VAC RMS / DC
 - Non-Agency Voltage Rating = 60 VAC RMS or VDC Maximum
- 3.2 Operating Current Rating = 0.5 Amps/contact with all contacts powered
- 3.3 Operating Temperature Range = -55° C to +85° C

4.0 Applicable Documents

- 4.1 FCI Specifications
 - 4.1.1 Engineering drawings
 - FCI product customer drawings (Various)
 - FCI customer drawing 10104444 (Recommended Via Drill Sizes and Plating)
 - 4.1.2 Process drawings
 - FCI product inspection drawings (Various)
 - 4.1.3 Application specification
 - GS-20-0305 (AirMax VSe Connector System, press-fit products)
 - 4.1.4 FCI Qualification Report
 - EL-2011-12-030
- 4.2 Industry or Trade Association standards

Telcordia GR-1217-CORE (Separable Electrical Connectors Used in Telecommunications Hardware)

NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Amphene	
TITLE			PAGE 4 of 13	REVISION E
	AirMax VSe®,	/S2® Connector System	AUTHORIZED BY Terry Luo	DATE 2021-02-03
				CTED

- 4.3 National or International Standards
 - 4.3.1 Flammability: UL94V-0 or similar applicable specification
 - 4.3.2 EIA 364: Electrical Connector/Socket Test Procedures Including Environmental Classifications.
 - 4.3.3 IEC 60512: Connectors for Electronic Equipment Tests and Measurement
- 4.4 FCI Laboratory Reports
 - To be added when available
- 4.5 Safety Agency Approvals
 - To be added when available

5.0 Requirements

5.1 Qualification

Connectors furnished under this specification shall be capable of meeting the qualification test requirements specified herein.

5.2 Material

The material for each component shall be as specified herein or equivalent.

- Contacts: Copper alloy
- Housings and IMLAs: High temperature thermoplastic; UL 94V-0 compliant
- 5.3 Finish

The finish for applicable components shall be as specified herein or equivalent.

- Contact Areas: Performance-based plating, qualified to meet the requirements of this specification, including Telcordia GR-1217-CORE (November 1995) Central Office test sequence
- Press-Fit Tails: Tin or Tin-Lead over Nickel
- 5.4 Design and Construction

Connectors shall be of the design, construction, and physical dimensions specified on the applicable product drawing. There shall be no cracks, burrs, or other physical defects that may impair performance.

NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Ampher	nol ICC
TITLE	AirMax VSe®,\	/S2® Connector System	PAGE 5 of 13 AUTHORIZED BY Terry Luo	REVISION E DATE 2021-02-03
				RICTED

6.0 Electrical Characteristics

6.1 Contact Resistance, Low Level (LLCR) – EIA 364-23

The low level contact resistance shall not initially exceed 60 milliohms (Backplane) or 120 milliohms (Coplanar). The low level contact resistance shall also not exceed 10 milliohms increase in resistance (from the initial measurement) after any treatment and/or environmental exposure.

The following details shall apply:

- a. Test Voltage 20 milli-volts DC max open circuit.
- b. Test Current Not to exceed 100 milli-amperes.
- c. Number of readings: 500 minimum
- 6.2 Insulation Resistance EIA 364-21

The insulation resistance of mated connectors shall not be less than 1000 M-ohms.

The following details shall apply:

- a. Test Voltage 500 volts DC (Sig-Sig & Sig-Grd), 200 volts DC (Grd-Grd)
- b. Electrification Time 60 seconds.
- c. Points of Measurement -Between adjacent contacts and between ground contacts within a column
- d. Number of readings: 30 (10 readings per loose-piece connector set)
- 6.3 Dielectric Withstanding Voltage EIA 364-20

There shall be no evidence of arc-over, insulation breakdown, or excessive leakage current > 0.5 mA. The following details shall apply:

- a. Test Voltage 500 volts (Sig-Sig & Sig-Grd), 200 volts (Grd-Grd) AC RMS, 60Hz.
- b. Test Duration 60 seconds.
- c. Test Condition 1 (760 Torr sea level).
- d. Points of Measurement Between adjacent contacts and ground contacts within a column.
- e. Number of readings: 30 (10 readings per loose-piece connector set)
- 6.4 Current Rating EIA 364-70

The temperature rise above ambient shall not exceed 30 deg C at any point in the system when all contacts are powered at 0.5 Amps

The following details shall apply:

- a. Ambient Conditions Still air at 25°C
- b. Thermocouple location mechanically attached to the base of the header mating contacts
- c. Copper trace weight: -1 oz
- d. Quantity and location of thermocouples 3 minimum (2 on interior column positions and 1 on an exterior column position)

GS-01-029

NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Ampher	nol ICC
TITLE			PAGE 6 of 13	REVISION E
	AirMax VSe®,\	/S2® Connector System	AUTHORIZED BY Terry Luo	DATE 2021-02-03
<u> </u>				RICTED

7.0 Mechanical Characteristics

7.1 Mating/Un-mating Force - EIA 364-13

The force to mate a receptacle connector and compatible AirMax VS® stitched header shall not exceed 0.50 N per contact. The un-mating force shall not be less than 0.15 N per contact.

The following details shall apply:

- a. Cross Head Speed 25.4 mm per minute.
- b. Utilize free floating fixtures.
- c. Number of mate/un-mate cycles: 3
- 7.2 Compliant Pin Insertion Force EIA 364-05

Fully populated connectors shall be applied to test boards in accordance with the AirMax VSe application specification GS-20-0305. Testing shall consist of two test groups in which three samples are inserted and withdrawn into the same test board in order to simulate connector repair cycles. The following details shall apply:

- a. Average force to insert one small EON (0.4mm PCB hole): 15 N maximum
- b. Average force to insert one standard EON (0.5mm PCB hole): 30 N maximum
- c. Number of connector assemblies to be tested: 6 (2 test groups, 3 samples each)
- d. Number of readings: 1 per connector assembly tested
- e. Test boards: Nominal diameter finished holes [Ø0.40 mm (small) and Ø0.50 mm (standard)] with immersion tin plating.
- f. Measure and record the test board's finished hole sizes prior to performing test.

7.3 Compliant Pin Retention Force – EIA 364-05

7.3.1 Immersion tin plating board with nominal diameter finished holes

Fully populated connectors shall be removed from test boards in accordance with AirMax VSe application specification GS-20-0305. Testing shall consist of two test groups in which two samples are inserted and withdrawn from the same test board in order to simulate connector repair cycles. The following details shall apply:

- a. Average force to remove one small EON (0.4mm PCB hole): 3.6 N minimum
- b. Average force to remove one standard EON (0.5mm PCB hole): 4.5 N minimum
- c. Number of connector assemblies to be tested: 4 (2 test groups, 2 samples each)
- d. Number of readings: 1 per connector assembly tested
- e. Test boards: Nominal diameter finished holes [Ø0.40 mm (small) and Ø0.50 mm (standard)] with immersion tin plating.

7.3.2 Test boards with maximum diameter finished holes

NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Amphene	
TITLE			PAGE 7 of 13	REVISION E
	AirMax VSe®,\	/S2® Connector System	AUTHORIZED BY Terry Luo	DATE 2021-02-03
				CTED

Fully populated connectors shall be removed from test boards in accordance with AirMax VSe application specification GS-20-0305. Testing shall consist of two test groups in which two samples are inserted and withdrawn from the same test board in order to simulate connector repair cycles. The following details shall apply:

- a. Average force to remove one EON: 3.0 N minimum
- b. Number of connector assemblies to be tested: 4 (2 test groups, 2 samples each)
- c. Number of readings: 1 per connector assembly tested
- d. Test boards: Maximum diameter finished holes [Ø0.45 mm (small) and Ø0.55 mm (standard)] boards
- 7.4 PCB Hole Deformation Radius and Remaining Cu Plating Thickness (compliant pin) EIA 364-96

Use PCB's with 0.40 mm (signal) and 0.50 mm (ground) diameter finished holes, with immersion tin plating, and 2.4 mm minimum overall thickness. Metallographic cross-sections shall be prepared parallel to the PCB surface (transverse section) to facilitate radial hole deformation measurement, photographs, and remaining Cu plating measurement.

Prior to cross-section preparation, perform 3 compliant pin insertions and 2 compliant pin withdrawals.

The measurements and photographs shall be performed at 0.3 mm, from the connector side PCB laminate (not copper) surface and at the center of the compliant pin section on a minimum of 10 holes of each size. The average (of 10 holes for each size) hole deformation radius shall be no greater than 37.5 μ m when measured from the drilled hole. The absolute maximum deformation radius shall not exceed 50 μ m. The minimum average (of 10 holes for each size) copper thickness remaining between the compliant pin and the printed wiring board laminate shall not be less than 7.5 μ m.

7.5 PCB Hole Wall Damage – EIA 364-96

Use PCB's with 0.40 mm (signal) and 0.50 mm (ground) diameter finished holes, with immersion tin plating, and 2.4 mm minimum overall thickness. Metallographic cross-sections shall be prepared perpendicular to the PCB surface (longitudinal section) and through the compliant section wear track to facilitate examination of the PTH.

Prior to cross-section preparation, perform 3 compliant pin insertions and 2 compliant pin withdrawals.

There shall be no copper cracks, separations between conductive interfaces, or laminate-to-copper separations. Inspect 10 pins/holes of each diameter.

NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Amphen	ol ICC
TITLE			PAGE 8 of 13	REVISION E
	AirMax VSe®,V	/S2® Connector System	AUTHORIZED BY Terry Luo	DATE 2021-02-03
				CTED

8.0 Environmental Conditions

After exposure to the following environmental conditions in accordance with the specified test procedure and/or details, the product shall show no physical damage and shall meet the electrical and mechanical requirements per paragraphs 6.0 and 7.0 as specified in the Table 1 test sequences. Unless specified otherwise, assemblies shall be mated during exposure.

- 8.1 Thermal Shock EIA 364-32.
 - a. Number of Cycles 5
 - b. Temperature Range Between -55°C and +85° C
 - c. Time at Each Temperature 30 minutes minimum
 - d. Transfer Time 30 seconds, maximum
- 8.2 Cyclical Humidity and Temperature EIA 364-31 method III. Samples are to be subjected to 50 cycles of 10-hour duration for a total of 500 hours.

A cycle consists of the following steps:

- a. 2 hour ramp from 25°C at 80%-98% RH to 65°C at 90%-98% RH
- b. 4 hour dwell at 65°C at 90%-98% RH
- c. 2 hour ramp down to 25°C at 80%-98% RH
- d. 2 hour dwell at 25°C at 80%-98% RH
- 8.3 Temperature Life EIA 364-17. Headers and receptacles shall remain mated without any electrical load
 - a. Test Temperature 85° C
 - b. Test Duration 500 hours
- 8.4 Mixed Flowing Gas corrosion (MFG) EIA 364-65, class IIA, 4-gas
 - a. Duration 20 days
 - b. Temperature 30°C
 - c. Humidity 70%
 - d. Un-mated backpanel connectors are to be exposed to gas mixture for 10 days, then mated and exposed for an additional 10 days. Coplanar, each gender shall be exposed for 10 days, then mated to unexposed connectors for an additional 10 days.
 - e. Gas compositions, per Central Office requirements:

<u>Gas Type</u>	Gas Concentration
NO ₂	200 ppb
Cl ₂	10 ppb
H ₂ S	10 ppb
SO ₂	100 ppb

NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Amphen	ol ICC
TITLE			PAGE 9 of 13	REVISION E
	AirMax VSe®,	/S2® Connector System	AUTHORIZED BY Terry Luo	DATE 2021-02-03
				CTED

- 8.5 Salt Spray EIA 364-26
 - a. Test Condition A
 - b. Duration 96 hours
 - c. Samples shall be mated during salt exposure
- 8.6 Vibration EIA 364-28, Test Condition II
 - a. Vibration Amplitude 1.5 mm double amplitude or 10G acceleration
 - b. Frequency Range 10 to 500 to 10 hertz
 - c. Sweep Time and Duration 15 minutes per sweep, 8 hours along each of three orthogonal axes (24 hours total)
 - d. Mounting Rigidly mount assemblies
 - e. No discontinuities greater than 1 microsecond
- 8.7 Mechanical Shock EIA 364-27, Test Condition H
 - a. Amplitude half sine 30G
 - b. Duration 11 milliseconds
 - c. Shocks 3 shocks along each of three orthogonal axes (18 shocks total)
 - d. Mounting Rigidly mount assemblies
 - e. LLCR readings Take LLCR measurements after shock in each axis
 - f. No discontinuities greater than 1 microsecond
- 8.8 Durability EIA 364-09
 - a. Number Cycles See table 1 (200 total mating cycles)
 - b. Cycling Rate 127 mm/min.
 - c. Use free floating fixtures
- 8.9 Dust EIA 364-91
 - a. Samples to be exposed to one-hour dust exposure
 - b. Using a benign dust composition number 1
 - c. Only unmated backpanel connectors shall be exposed to dust. For co-planar applications, both connectors shall be exposed to dust and then mated to unexposed connectors.
- 8.10 Disturb Perform in accordance with Telcordia GR-1217-CORE, November 1995, section 9.1.3.3 paragraph 7. The mated connectors shall be subjected to an interface disturbance that consists of slightly un-mating the sample approximately 0.10 mm. The sample is then reseated and measurements are taken.

NUMBER	GS-12-0956	PRODUCT SPECIFICATION	Amphe	nol ICC
TITLE			PAGE 10 of 13	REVISION
	AirMax VSe®,\	/S2® Connector System	AUTHORIZED BY Terry Luo	DATE 2021-02-03
L				RICTED

9.0 Quality Assurance Provisions

9.1 Equipment Calibration

All test equipment and inspection facilities used in the performance of any test shall be maintained in a calibration system in accordance with ANSI Z-540 and ISO 9000.

9.2 Inspection Conditions

Unless otherwise specified herein, all inspections shall be performed under the following ambient conditions:

- a. Temperature: 25 +/- 5 deg C
- b. Relative Humidity: 30% to 60%
- c. Barometric Pressure: Local ambient
- 9.3 Sample Quantity and Description

The test sequences for qualification testing are shown in table 1 and the connector sample sizes for 5pair connectors is shown in Table 2. The number of readings is specified in the description for each test. For connector sizes with fewer contacts than 5-pair connectors, additional samples may be required to meet the minimum number of readings for specific tests.

- 9.4 Acceptance
 - a. Electrical and mechanical requirements placed on test samples as indicated in paragraphs 6.0 and 7.0 shall be established from test data using appropriate statistical techniques or shall otherwise be customer specified, and all samples tested in accordance with this product specification shall meet the stated requirements.
 - b. Failures attributed to equipment, test setup, or operator error shall not disqualify the product. If product failure occurs, corrective action shall be taken and samples resubmitted for qualification.
- 9.5 Qualification Testing

Qualification testing shall be performed on sample units produced with equipment and procedures normally used in production. The test sequences shall be as shown in the qualification test table. Data shall be provided with the samples noting production history: production lot codes for components and assemblies, print revisions for components and assemblies, and plating composition and thickness.

9.6 Re-Qualification Testing

If any of the following conditions occur, the responsible product engineer shall initiate requalification testing consisting of all applicable parts of the qualification test matrix.

- a. A significant design change is made to the existing product which impacts the product form, fit or function. Examples of significant changes shall include, but not be limited to, changes in the plating material composition or thickness, contact force, contact surface geometry, insulator design, contact base material, or contact lubrication requirements.
- b. A significant change is made to the manufacturing process which impacts the product form, fit or function.
- c. A significant event occurs during production or end use requiring corrective action to be taken relative to the product design or manufacturing process.

PRODUCT SPECIFICATION

Amphenol ICC

TITLE

AirMax VSe®,VS2® Connector Syst	em

TYPE

PAGE REVISION
11 of 13 E
AUTHORIZED BY DATE
Terry Luo 2021-02-03
CLASSIFICATION
UNRESTRICTED

7

Current

Rating

1,3

2

TEST GROUP ID ► \mathbf{P}^1 4 ² 5 ³ 1 2 3a 3b 6 Press-Fit Desian Mixed Thermal Thermal Vibration Evaluation Verification Temp Salt TEST DESCRIPTION SECTION Flowing Shock & Shock & & Mech. & Mating / for Product Life Spray Gas Humidity Humidity Shock Un-mating Extension Forces DESIGN AND 5.4 1,7 1,16 1,5 1,11 1,14 1,14 1 1,5 CONSTRUCTION MATE HEADER AND 2 2.8 2 2.10 --2.8 RECEPTACLE UN-MATE HEADER AND 6 8 6 ---RECEPTACLE ELECTRICAL: 3,5,7,11, 3,5,9,11, 3,5,9,11, LOW LEVEL CONTACT 6.1 4,6 2,4 2.4 13,15 13 13 RESISTANCE INSULATION 6.2 3,6,9 RESISTANCE DIELECTRIC 6.3 4,7,10 WITHSTANDING VOLTAGE 6.4 CURRENT RATING MECHANICAL: MATING / UN-MATING 7.1 3 7 FORCE COMPLIANT PIN 72 2,4,6 INSERTION FORCE COMPLIANT PIN 7.3 3,5 RETENTION FORCE PCB HOLE 7.4 8 DEFORMATION RADIUS 7.5 9 PCB WALL DAMAGE ENVIRONMENTAL: THERMAL SHOCK 81 5 4 **CYCLICAL HUMIDITY &** 8 12 8.2 TEMPERATURE TEMPERATURE LIFE 8.3 3 MFG, UN-MATED, 10-8.4 7 DAYS MFG, MATED, 10-DAYS 8.4 10 SALT SPRAY 8.5 3 VIBRATION 8.6 10 MECHANICAL SHOCK 8.7 12 DURABILITY, 99-CYCLES 8.8 5 6 4 4,14 DUST CONTAMINATION 8.9 9 7

9.7 Qualification Test Tables – See note 4

Table 1: Qualification Test Matrix

12

8.10

DISTURB

© 2018 AICC Form E-3701 – Revision E

GS-12-0956

Amphenol ICC

TITLE

NUMBER

AirMax	VSe®,VS2®	Connector	System
			-,

TYPE

PAGE	REVISION
12 of	13 E
AUTHORIZED BY Terry	Luo 2021-02-03
	NRESTRICTED

TEST GROUP ID ►	P ¹	1	2	3a	3b	4 ²	5 ³	6	7
COMPONENT DESCRIPTION	Design Verification for Product Extension	Mixed Flowing Gas	Temp Life	Thermal Shock & Humidity	Thermal Shock & Humidity	Vibration & Mech. Shock	Press-Fit Evaluation & Mating / Un- mating Forces	Salt Spray	Current Rating
Number of receptacles	4	4	4	3	4	4	6	4	3
Number of headers	4	4	4	3	4	4	2	4	3
LLCR Board Sets	4	4	4		4	3		4	
Continuity Board Set						1			3
Receptacle Mechanical Boards							2		
Header Mechanical Boards							2		

PRODUCT SPECIFICATION

Table 2: Qualification Sample Requirements

Notes:

- 1. Group P is not required for a full qualification. Group P is a design verification sequence for product extensions after a full qualification has been completed.
- 2. For test group 4, LLCR is measured on 3 sample sets and one set is used for discontinuity monitoring.
- 3. For test group 5, only the receptacle connector needs to be tested for compliant pin insertion and withdrawal forces and cross sectioned for the PCB hole wall damage / deformation requirements. Headers have been previously qualified per FCI product specification GS-12-239.

Amphenol ICC

TITLE

AirMax VSe®,VS2® Connector System

TYPE

PAGE REVISION

 13 of 13
 E

 AUTHORIZED BY
 DATE

 Terry Luo
 2021-02-03

 CLASSIFICATION
 UNRESTRICTED

REVISION RECORD

Rev	Page	Description	EC#	Date
Α	All	Initial Release	-	2012-02-09
В	6	Modified the requirement for mating force (section 7.1)	ECN-ELX-V- 11997	2012-06-21
С	All	Add VS2 connector, Modified the operating voltage rating and trade mark, Compliant Pin Insertion Force & retention force (section 3.0,7.2&7.3)	ECN-ELX-V- 15716	2014-04-23
D	All 6,7	Update template with new AICC logo Add compliant pin retention force spec for maximum diameter finished holes boards(section 7.3.2)	ECN-ELX- DG-33303	2019-04-22
E	3	Detail operating voltage rating by distinguishing agency and non- agency(section 3.1)	ECN-ELX- DG-39900	2021-01-26